State Grid Tongfu Microelectronics

TongFu Microelectronics Co. Ltd. 002156 (China: ... dual flat no-lead, quad flat no-lead, ball grid array, flip chip, and bump series. The company was founded om February 4, 1994 and is ...

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(TFME: TongFu Microelectronics Co.,Ltd.) ??: ?????? (???????) ???: 1997?: CEO: Shi Lei ?? (2008?4?-) ????: 13,594? ????: ??: ? ...

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TongFu Microelectronics Co., Ltd. engages in the business of integrated circuit assembling and testing. ... dual flat no-lead, quad flat no-lead, ball grid array, flip chip, and bump series. The ...

Tongfu Microelectronics engages in products, technologies and services in many fields, including network communication, mobile terminals, household appliances, AI, auto electronics, etc.....More

TongFu''s patenting activity related to hybrid bonding. TongFu MicroElectronics, formerly known as Nantong Fujitsu Microelectronics (NFME), has a long-standing presence in ...

Tongfu Microelectronics Co.,Ltd. was established in October 1997 and listed on the Shenzhen Stock Exchange in August 2007. Its total assets are more than 16 billion yuan. Headquartered in Nantong, Jiangsu Province, Tongfu ...

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